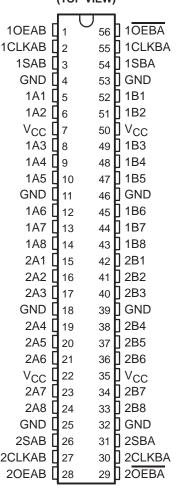
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- **Members of the Texas Instruments** Widebus™ Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- **Support Mixed-Mode Signal Operation** (5-V Input and Output Voltages With 3.3-V V_{CC})
- **Support Unregulated Battery Operation** Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) $< 0.8 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Distributed V_{CC} and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- Flow-Through Architecture Optimizes PCB
- Latch-Up Performance Exceeds 500 mA Per **JESD 17**
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- **Package Options Include Plastic Shrink** Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

SN54LVTH16652...WD PACKAGE SN74LVTH16652 . . . DGG OR DL PACKAGE (TOP VIEW)



description

The 'LVTH16652 devices are 16-bit bus transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices can be used as two 8-bit transceivers or one 16-bit transceiver.

Output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select whether real-time or stored data is transferred. A low input level selects real-time data, and a high input level selects stored data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'LVTH16652 devices.



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description (continued)

Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) inputs, regardless of the levels on the select-control or output-enable inputs. When SAB and SBA are in the real-time transfer mode, it also is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last level configuration.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

These devices are fully specified for hot-insertion applications using $I_{\rm off}$ and power-up 3-state. The $I_{\rm off}$ circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

The SN54LVTH16652 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LVTH16652 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

| | | INP | UTS | | | DATA | 4 I/O† | ODED ATION OD EUNOTION |
|------|------|------------|------------|-----|-----|--------------------------|--------------------------|---|
| OEAB | OEBA | CLKAB | CLKBA | SAB | SBA | A1–A8 | B1-B8 | OPERATION OR FUNCTION |
| L | Н | H or L | H or L | Х | Х | Input | Input | Isolation |
| L | Н | \uparrow | \uparrow | X | Х | Input | Input | Store A and B data |
| Х | Н | 1 | H or L | Х | Х | Input | Unspecified [‡] | Store A, hold B |
| Н | Н | \uparrow | \uparrow | χ‡ | X | Input | Output | Store A in both registers |
| L | Х | H or L | ↑ | Х | Х | Unspecified [‡] | Input | Hold A, store B |
| L | L | \uparrow | \uparrow | X | χ‡ | Output | Input | Store B in both registers |
| L | L | Х | Χ | Х | L | Output | Input | Real-time B data to A bus |
| L | L | X | H or L | X | Н | Output | Input | Stored B data to A bus |
| Н | Н | Х | Х | L | Х | Input | Output | Real-time A data to B bus |
| Н | Н | H or L | X | Н | X | Input | Output | Stored A data to B bus |
| Н | L | H or L | H or L | Н | Н | Output | Output | Stored A data to B bus and stored B data to A bus |

[†] The data-output functions may be enabled or disabled by a variety of level combinations at OEAB or OEBA. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



[‡] Select control = L; clocks can occur simultaneously.

Select control = H; clocks must be staggered to load both registers.

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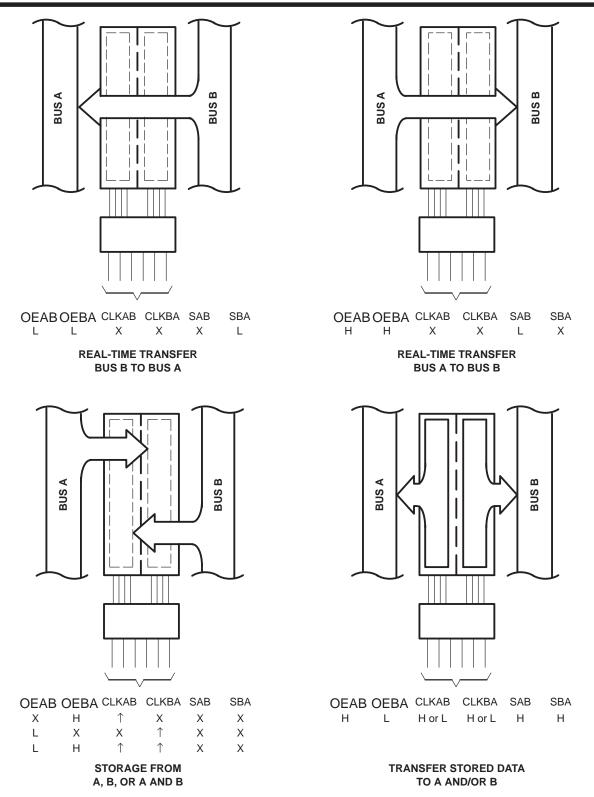
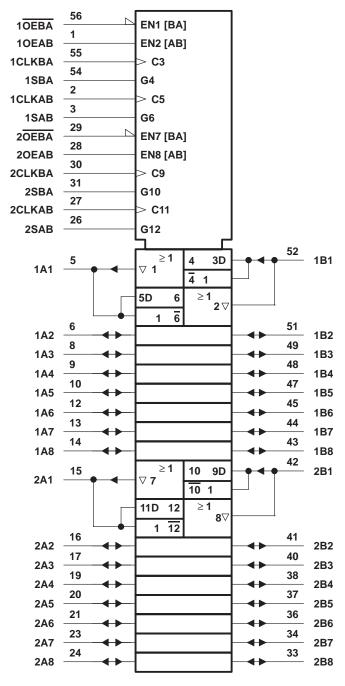


Figure 1. Bus-Management Functions



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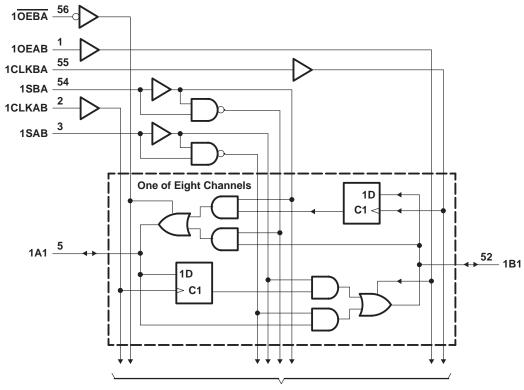
logic symbol†



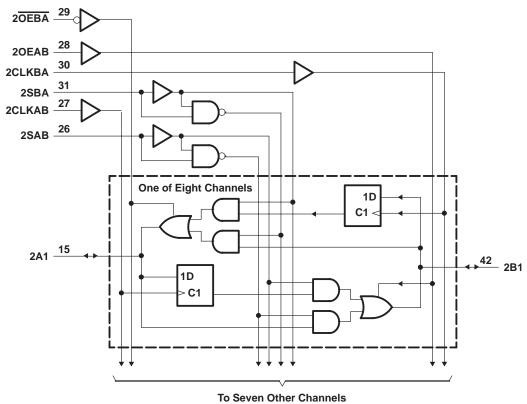
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



To Seven Other Channels





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| Supply voltage range, V _{CC} | |
|---|---------------------------|
| Input voltage range, V _I (see Note 1) | |
| Voltage range applied to any output in the high-impedance | |
| or power-off state, V _O (see Note 1) | –0.5 V to 7 V |
| Voltage range applied to any output in the high state, VO (see Note 1) | 0.5 V to V_{CC} + 0.5 V |
| Current into any output in the low state, IO: SN54LVTH16652 | 96 mA |
| SN74LVTH16652 | |
| Current into any output in the high state, IO (see Note 2): SN54LVTH16652 | 48 mA |
| | 64 mA |
| Input clamp current, I _{IK} (V _I < 0) | –50 mA |
| Output clamp current, I _{OK} (V _O < 0) | –50 mA |
| Package thermal impedance, θ _{JA} (see Note 3): DGG package | 81°C/W |
| DL package | |
| Storage temperature range, T _{stq} | –65°C to 150°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

| | | | SN54LVTI | 116652 | SN74LVTI | H16652 | UNIT |
|---------------------|------------------------------------|-----------------|----------|--------|----------|--------|------|
| | | | MIN | MAX | MIN | MAX | UNIT |
| VCC | Supply voltage | | 2.7 | 3.6 | 2.7 | 3.6 | V |
| VIH | High-level input voltage | 2 | 2 | 2 | | V | |
| V _{IL} | Low-level input voltage | | 0.8 | | 0.8 | V | |
| VI | Input voltage | | 5.5 | | 5.5 | V | |
| loн | High-level output current | | 1 | -24 | | -32 | mA |
| loL | Low-level output current | 2 | 48 | | 64 | mA | |
| Δt/Δν | Input transition rise or fall rate | Outputs enabled | 70, | 10 | | 10 | ns/V |
| Δt/ΔV _{CC} | Power-up ramp rate | • | 200 | · | 200 | | μs/V |
| T _A | Operating free-air temperature | | -55 | 125 | -40 | 85 | °C |

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST OF | SN5 | 4LVTH16 | 6652 | SN7 | 4LVTH16 | 6652 | UNIT | |
|----------------------|--|--|---------------------------------------|--------------------|--|-------|--------------------|-----------------|------|------|
| PAR | RAMETER | 1551 CC | ONDITIONS | MIN | TYP† | MAX | MIN | TYP† | MAX | UNII |
| VIK | | $V_{CC} = 2.7 \text{ V},$ | | | -1.2 | | | -1.2 | V | |
| | | $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$ | $I_{OH} = -100 \mu A$ | V _{CC} -0 | .2 | | V _{CC} -0 | .2 | | |
| V | | $V_{CC} = 2.7 \text{ V},$ | I _{OH} = -8 mA | 2.4 | | | 2.4 | | | V |
| VOH | | V _{CC} = 3 V | I _{OH} = -24 mA | 2 | | | | | | V |
| | | VCC = 3 V | I _{OH} = -32 mA | | | | 2 | | | |
| | | V _{CC} = 2.7 V | I _{OL} = 100 μA | | | 0.2 | | | 0.2 | |
| | | VCC = 2.7 V | I _{OL} = 24 mA | | | 0.5 | | | 0.5 | |
| Vol | | | I _{OL} = 16 mA | | | 0.4 | | | 0.4 | V |
| VOL | | V _{CC} = 3 V | $I_{OL} = 32 \text{ mA}$ | | | 0.5 | | | 0.5 | ٧ |
| | | VCC = 3 V | $I_{OL} = 48 \text{ mA}$ | | 0.55 | | | | | |
| | | | I _{OL} = 64 mA | | | | | 0.55 | | |
| | Control inputs $V_{CC} = 0 \text{ or } 3.6 \text{ V},$ | | V _I = 5.5 V | | | \$ 10 | | | 10 | |
| | Control inputs | $V_{CC} = 3.6 \text{ V},$ | $V_I = V_{CC}$ or GND | | Ş | ±1 | | | ±1 | |
| lį | A or B ports‡ | V _{CC} = 3.6 V | V _I = 5.5 V | 20 | | | | | 20 | μΑ |
| | | | VI = VCC | | 5 | 1 | | | 1 | |
| | | | V _I = 0 | -5 | | | | -5 | | |
| l _{off} | | $V_{CC} = 0$, | V_I or $V_O = 0$ to 4.5 V | 0% |) The state of the | | | | ±100 | μΑ |
| | | V _{CC} = 3 V | V _I = 0.8 V | 75 | | | 75 | | | |
| I _{I(hold)} | A or B ports | VCC = 3 V | V _I = 2 V | -75 | – 75 | | -75 | - 75 | | μΑ |
| | | V _{CC} = 3.6 V§, | $V_{I} = 0 \text{ to } 3.6 \text{ V}$ | | | | | | ±500 | |
| I _{OZPU} | | $\frac{\text{V}_{\text{CC}}}{\text{OE/OE}} = 0 \text{ to } 1.5 \text{ V}, \text{ V}_{\text{O}} = 0.5 \text{ V to } 3 \text{ V},$ | | | | ±100* | | | ±100 | μΑ |
| lozpd | | $\frac{\text{V}_{\text{C}}\text{C}}{\text{OE}/\text{OE}} = 1.5 \text{ V to 0, V}_{\text{O}} = \frac{\text{OE}}{\text{OE}}$ | 0.5 V to 3 V, | | | ±100* | | | ±100 | μΑ |
| lcc | | V _{CC} = 3.6 V, | Outputs high | | | 0.19 | | | 0.19 | |
| | | $I_{O} = 0$, | Outputs low | | 5 0.19 | | 5 | | mA | |
| | | $V_I = V_{CC}$ or GND | Outputs disabled | | | | | 0.19 | | |
| ΔI _{CC} ¶ | | $V_{CC} = 3 \text{ V to } 3.6 \text{ V}$, One input at $V_{CC} - 0.6 \text{ V}$, Other inputs at V_{CC} or GND | | | | 0.2 | | | 0.2 | mA |
| Ci | | V _I = 3 V or 0 | | | 4 | | | 4 | | pF |
| C _{io} | | V _O = 3 V or 0 | | | 10 | | | 10 | | pF |

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested. † All typical values are at $V_{CC}=3.3~V$, $T_{A}=25^{\circ}C$. ‡ Unused pins at V_{CC} or GND



[§] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

| | | | SN54LVTH16652 | | | | SN74LVTH16652 | | | | |
|-----------------|---------------------------------|-----------|-------------------|--------------|-------------------|-------|-------------------------|--------------|-------------------|-------|------|
| | | | V _{CC} = | 3.3 V 3 V | V _{CC} = | 2.7 V | V _{СС} ± 0. | = 3.3 3 V | V _{CC} = | 2.7 V | UNIT |
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| fclock | Clock frequency | | | 150 | | 150 | | 150 | | 150 | MHz |
| t _W | Pulse duration, CLK high or low | | 3.3 | | 3.3 | | 3.3 | | 3.3 | | ns |
| | Setup time, | Data high | 1.2 | | 1.5 | | 1.2 | | 1.5 | | ne |
| t _{su} | A or B before CLKAB↑ or CLKBA↑ | Data low | 2 | o Po | 2.8 | | 2 | | 2.8 | | ns |
| 4. | Hold time, | Data high | 0.5 | ,6,, | 0 | | 0.5 | | 0 | | ns |
| ^t h | A or B after CLKAB↑ or CLKBA↑ | Data low | 0.5 | | 0.5 | | 0.5 | | 0.5 | | 115 |

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 2)

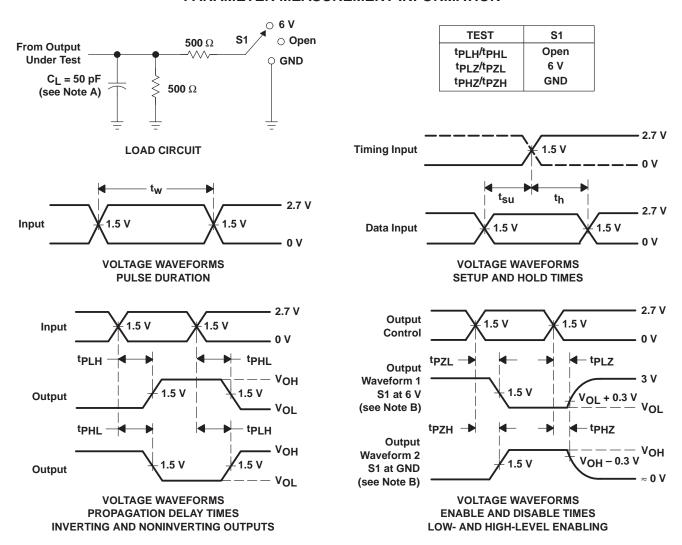
| | | | SN54LVTH16652 | | | | SN74LVTH16652 | | | | | | | |
|------------------|-----------------|----------------|---------------|--------|-------------------------|-----|------------------------------------|------------------|-----|-------------------------|-----|------|-----|----|
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | 00 - | | V _{CC} = 2.7 V | | V _{CC} = 3.3 V ± 0.3 V | | V | V _{CC} = 2.7 V | | UNIT | | |
| | | | MIN | MAX | MIN | MAX | MIN | TYP [†] | MAX | MIN | MAX | | | |
| f _{max} | | | 150 | | 150 | | 150 | | | 150 | | MHz | | |
| ^t PLH | CLK | B or A | 1.3 | 4.5 | | 5 | 1.3 | 2.7 | 4.2 | | 4.7 | ns | | |
| ^t PHL | CLK | BULK | 1.3 | 4.5 | | 5 | 1.3 | 2.8 | 4.2 | | 4.7 | 115 | | |
| ^t PLH | A or B | B or A | 1 | 3.6 | | 4.1 | 1 | 2.4 | 3.4 | | 3.9 | ns | | |
| ^t PHL | AOIB | BULK | 1 | 3.6 | EIN | 4.1 | 1 | 2.1 | 3.4 | | 3.9 | 115 | | |
| ^t PLH | SAP or SPA | SAB or SBA | SAR or SRA | B or A | 1 | 4.7 | Ny | 5.6 | 1 | 2.7 | 4.5 | | 5.4 | ns |
| ^t PHL | SAB OI SBA | BULA | 1 | 4.7 | y _o | 5.6 | 1 | 3 | 4.5 | | 5.4 | 115 | | |
| ^t PZH | OED4 | А | 1 | 4.5 | • | 5.4 | 1 | 2.4 | 4.3 | | 5.2 | ns | | |
| t _{PZL} | OEBA | A | 1 | 4.5 | | 5.4 | 1 | 2.3 | 4.3 | | 5.2 | 115 | | |
| ^t PHZ | <u></u> | А | 2 | 5.8 | | 6.3 | 2 | 3.9 | 5.6 | | 6.1 | ns | | |
| t _{PLZ} | OEBA | A | 2 | 5.6 | | 6.3 | 2 | 3.4 | 5.4 | | 6.1 | 115 | | |
| ^t PZH | OFAR | В | 1.3 | 4.4 | | 5.1 | 1.3 | 2.7 | 4.2 | | 4.9 | ns | | |
| tPZL | OEAB | D | 1.3 | 4.4 | | 5.1 | 1.3 | 2.6 | 4.2 | | 4.9 | 115 | | |
| t _{PHZ} | OEAB | 0545 | В | 1.6 | 5.8 | | 6.5 | 1.3 | 3.5 | 5.5 | | 6.2 | nc | |
| t _{PLZ} | | Б | 1.6 | 5.8 | | 6.5 | 1.3 | 3.2 | 5.5 | | 6.2 | ns | | |

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms





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PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|-------------------|-----------------------|-----------------|--------------------|------|----------------|-------------------------|------------------|------------------------------|
| 74LVTH16652DGGRE4 | ACTIVE | TSSOP | DGG | 56 | 2000 | Pb-Free (RoHS) | CU NIPDAU | Level-1-250C-UNLIM |
| 74LVTH16652DLRG4 | ACTIVE | SSOP | DL | 56 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LVTH16652DGGR | ACTIVE | TSSOP | DGG | 56 | 2000 | Pb-Free (RoHS) | CU NIPDAU | Level-1-250C-UNLIM |
| SN74LVTH16652DL | ACTIVE | SSOP | DL | 56 | 20 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74LVTH16652DLR | ACTIVE | SSOP | DL | 56 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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